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SEP 17 2007

Application No.: 10/810,436

Docket No.: JCLA12013-R

AMENDMENTSIn The Claims:

Please amend the claims as follows:

Claim 1. (currently amended) A chip package, for disposing on a printed circuit board (PCB), the chip package comprising:

a chip, having an active surface and a plurality of bond pads, said bond pads being on said active surface;

a rigid cover, on said active surface, said rigid cover exposing said plurality of bond pads above said active surface, wherein the rigid cover is located between the chip and the PCB;

an adhesive layer, disposed between the chip and the rigid cover, and the rigid cover is adhered to the chip via the adhesive layer; and

a plurality of contacts, electrically connected to said plurality of bond pads respectively, wherein the contacts are conductive bumps, and the contacts are connected to the PCB.

Claim 2. (withdrawn) The chip package of claim 1, wherein said chip includes a redistribution layer on said active surface to form said plurality of bond pads.

Claim 3. (original) The chip package of claim 1, wherein said rigid cover is adhered to said active surface.

Claim 4. (original) The chip package of claim 1, wherein said rigid cover having a periphery adhered to said active surface.

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Claim 5. (original) The chip package of claim 1, wherein the material of said rigid cover includes a conducting material, an insulating material, or a transparent material.

Claim 6. (previously presented) The chip package of claim 1, wherein said plurality of contacts are disposed on said plurality of bond pads respectively, and the heights of said contacts relative to said active surface are larger than the height of said rigid cover relative to said active surface.

Claim 7. (original) The chip package of claim 1, wherein said plurality of bond pads is disposed on the circumference of said active surface.

Claim 8. (previously presented) The chip package of claim 7, wherein said active surface is a rectangle, and said plurality of bond pads are disposed on one side of said rectangle.

Claim 9. (withdrawn) The chip package of claim 7, wherein said chip has a backside relative to said active surface and a plurality of connecting lines, each of said plurality of connecting lines having an end connected to one of said plurality of bond pads, said plurality of connecting lines extending to said backside via a lateral side of said chip and forming a plurality of terminal pads on said backside respectively.

Claim 10. (withdrawn) The chip package of claim 9, wherein said plurality of terminal pads is disposed on the circumference of said backside.

Claim 11. (withdrawn) The chip package of claim 9, wherein said plurality of terminal pads is disposed on said backside of said chip as an area array.

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Claim 12. (withdrawn) The chip package of claim 9, wherein said lateral side of said chip includes a concave surface and portions of said connecting lines are on said concave surface respectively.

Claim 13. (withdrawn) The chip package of claim 9, further comprising a plurality of contacts on said terminal pads respectively.

Claim 14. (withdrawn) The chip package of claim 1, wherein said plurality of bond pads are disposed on said active surface as an area array, said rigid cover having a plurality of openings to expose said bond pads respectively.

**Claims 15-23 (cancelled)**

Claim 24 (new) The chip package of claim 1, wherein said bond pads are disposed on said active surface as an array and said rigid cover located above said active surface has a plurality of openings corresponding to said bond pads and exposing said bond pads respectively.